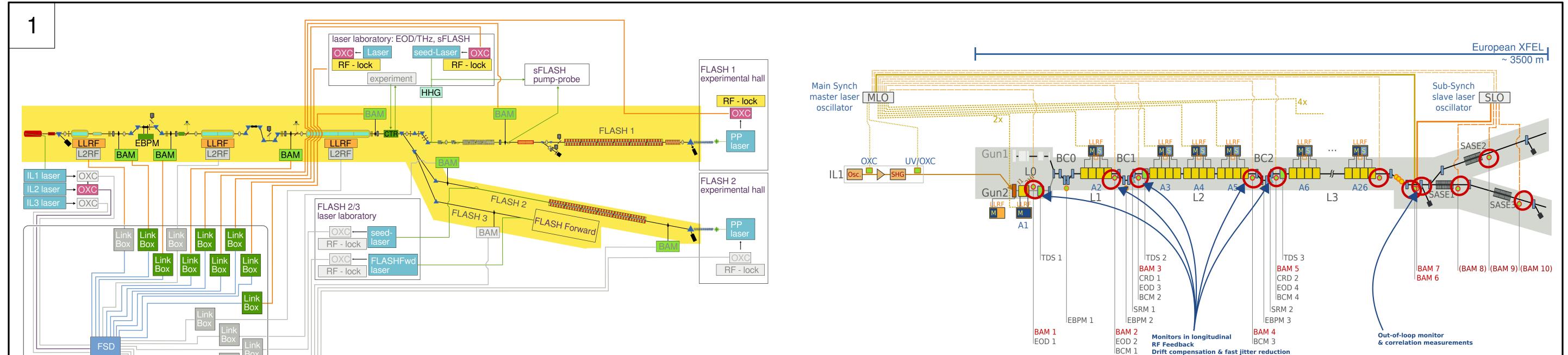
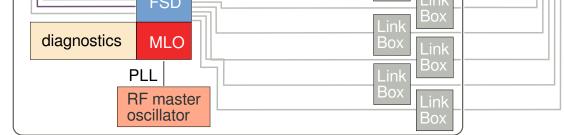
The Bunch Arrival Time Monitor at FLASH and European XFEL.

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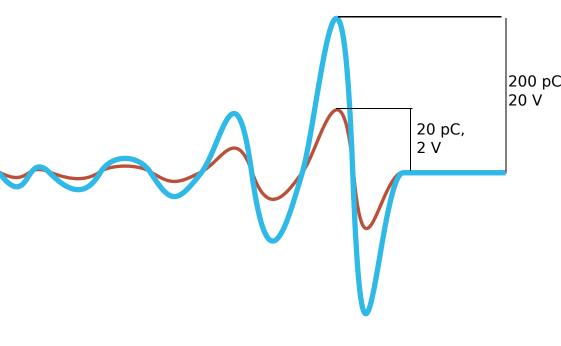
- > Bunch Arrival Time Monitor (BAM) crucial component of the Beam Based Feedback.
- > Fast intra bunch-train feedback as well as slow feedback is provided.
- > Currently 3 BAM systems are in operation at FLASH and 5 at the European XFEL [1][2].

BAM is composed of 3 main parts

- RF Unit: RF signal generated by the electron bunch collected by pickups along the beam line [3].
- Electro-Optical Unit: it combines the RF signals with timing-stabilized laser pulses to provide the bunch arrival time [4].
- Data Acquisition System [5].
- The laser-based synchronization system provides 216 MHz laser pulses used in the measurement.

Rf Unit

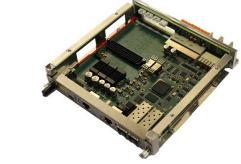
- Signals of 2 opposite pick-ups combined
- to reduce dependency on the transversal beam position (RF signal).
- The RF signal strength is a function of the bunch charge.
- One RF signal is fed to a low pass filter and a power limiter in order to be able to measure the arrival time for bunch charge up to nC.



BAM Box Generation 3 2

- > 19" box rack-mount chassis.
- Compartment with fibre-optics actively temperature stabilized
- (2 temperature controllers) and passively humidity stabilized.
- > Laser Diode Driver for laser pulse amplification (LDD board).
- > Power management (FRED Board).
- Box management (TMCB Board).
- > Setting temperature controllers.
- > Bias Voltage for EOM.
- > Temperature and humidity sensors.
- > Control Optical Switch.
- Three linear stage for optical delay lines (OWIS).

Electronics & Software, Standalone Boards



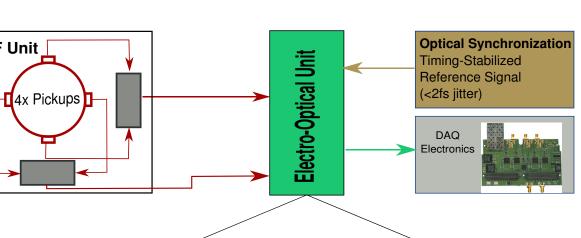
- > Temperature Monitoring and **Control Board (TMCB).**
- > General Purpose I/O Board used for Box Management
- > 14 ADC and 10 General Purpose Inputs and Outputs (GPIOs).
- > Interface for 2 temperature controllers.
- > The same hardware is shared with



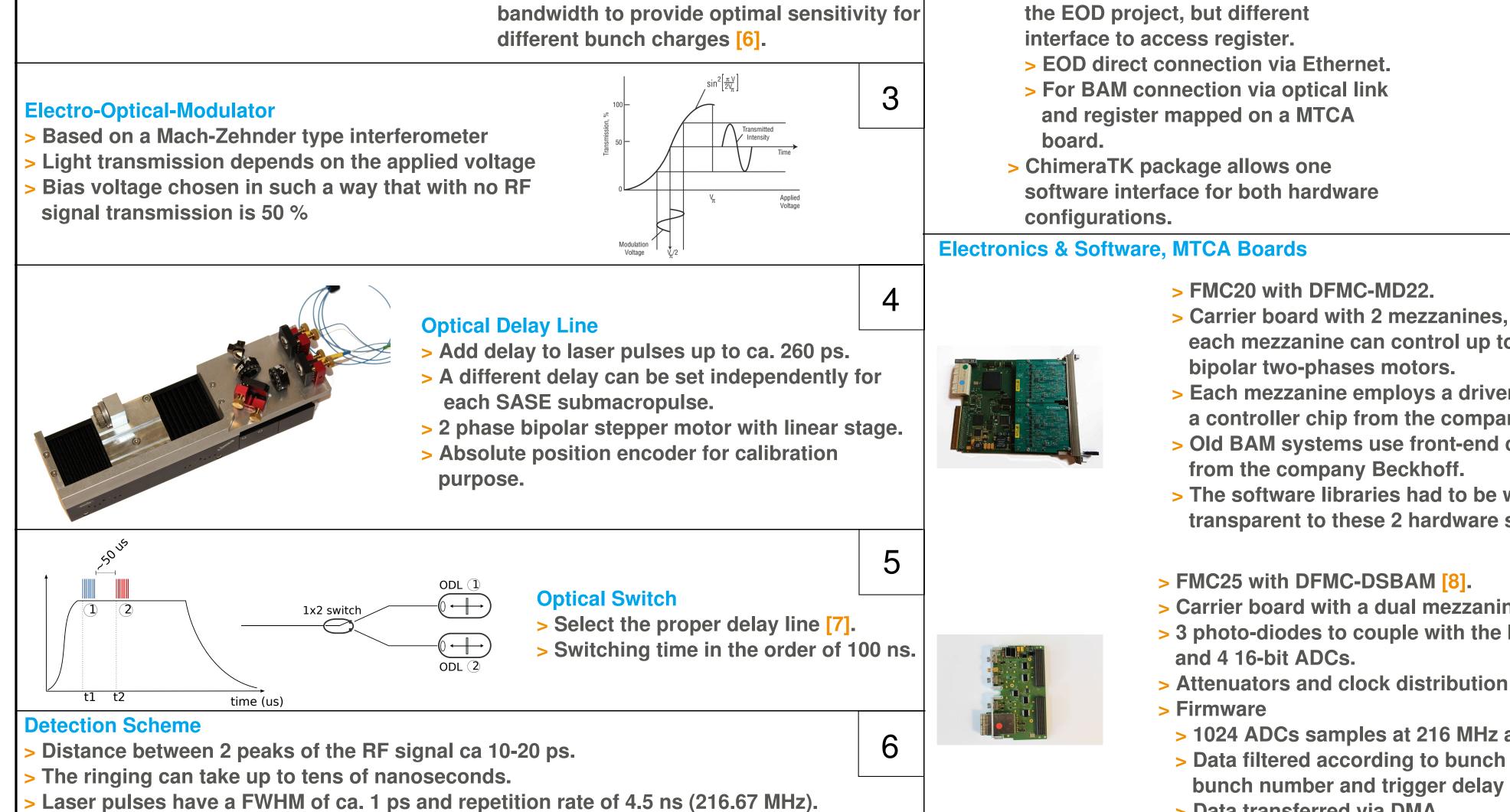




- > Laser Diode Driver (LDD)
- > Carrier board and up to 8 mezzanines.
- > Each mezzanine provides the current source for a Laser Diode
- > Ethernet and CAN bus interface is available on each mezzanine
- > Temperature controller for the laser diode
- > Two operation modes: constant current or constant diode output power. > Interface based on TCP/IP protocols with the usage of binary packages > command lines and QT interface also available



- \Box
- **Electro-Optical Unit**
- > Optical amplifier.
- > Two or more Optical Delay Lines to adjust the delay for each SASE submacropulse independently.
- > Two Electro-Optical Modulators (EOMs) to cross-correlate the RF signals with laser pulses, each EOM with different RF



- Depending on the synchronization between laser pulses and RF signals, pulse height can be modulated.
- modulation occurs.

- each mezzanine can control up to two
- > Each mezzanine employs a driver and a controller chip from the company Trinamic.
- > Old BAM systems use front-end control
- > The software libraries had to be written to be transparent to these 2 hardware setups.

> Fuse Relay Board (FRED).

Individual fuse and current

> Connection based on telnet

> Qt Interface also available.

to set the channels.

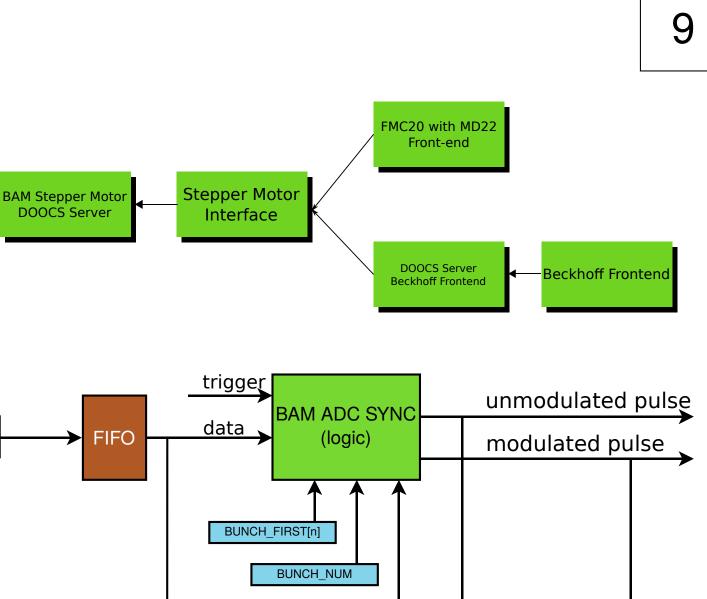
session and string commands

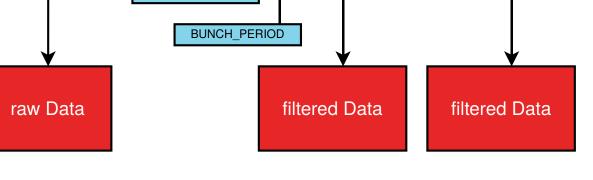
voltage channel.

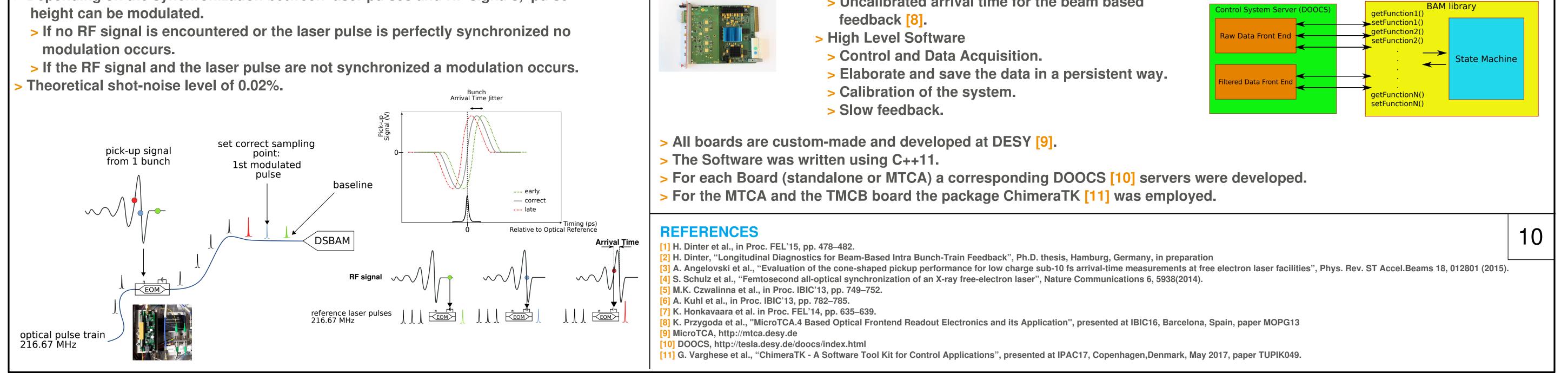
limitations.

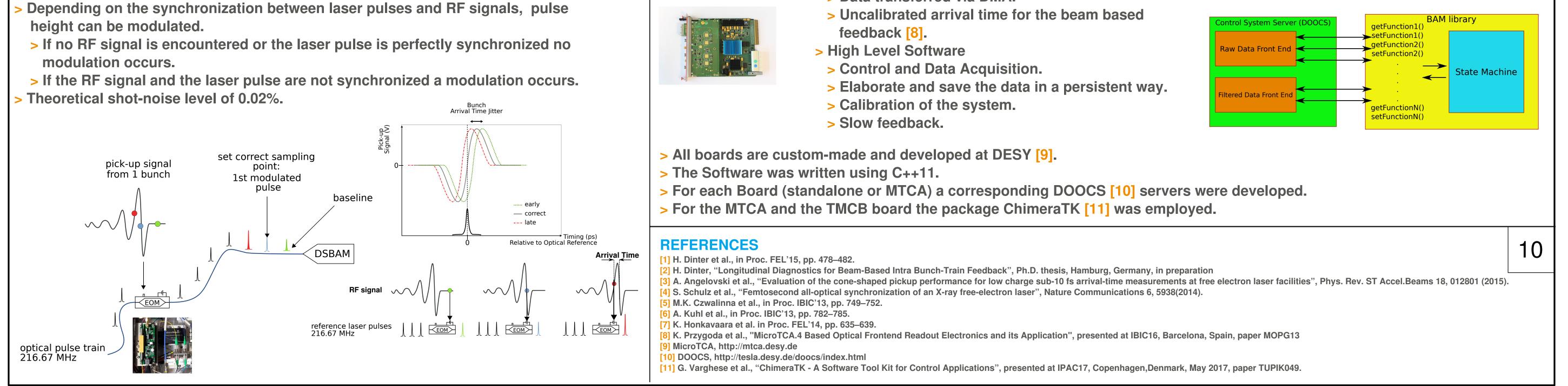
> Control and monitor up to 8 DC

- > FMC25 with DFMC-DSBAM [8].
- > Carrier board with a dual mezzanine.
- > 3 photo-diodes to couple with the laser pulses.
- > Attenuators and clock distribution chip.
- > 1024 ADCs samples at 216 MHz are stored in RAM.
- > Data filtered according to bunch repetition rate, bunch number and trigger delay stored in RAM.
- > Data transferred via DMA.









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16th International Conference on Accelerator and Large Experimental Control Systems, Barcelona, Spain **Poster ID : TUPHA125 Feedback Control and Process Tuning**

